

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

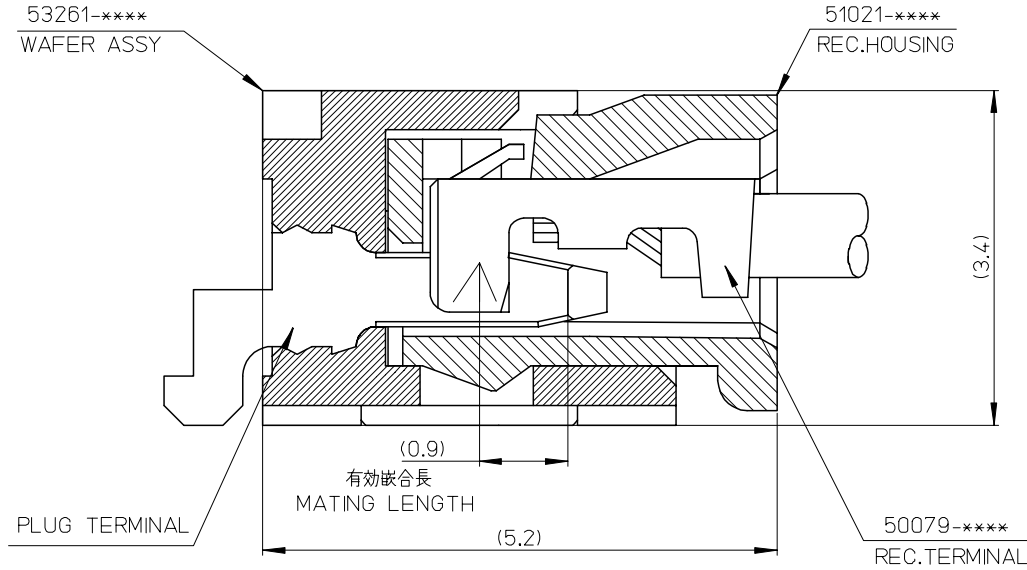
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART			
	ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-51021-002		SHEET NO. 1 OF 1	

9

8

7

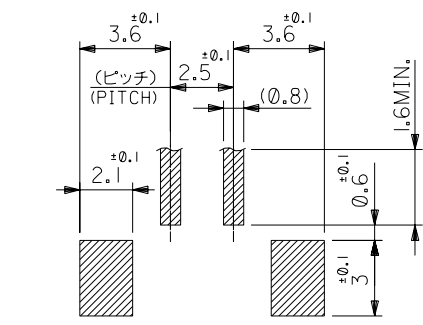
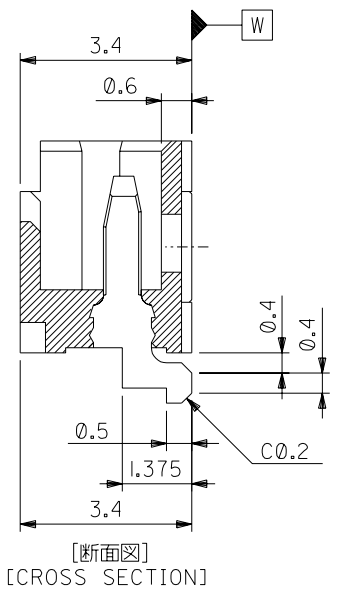
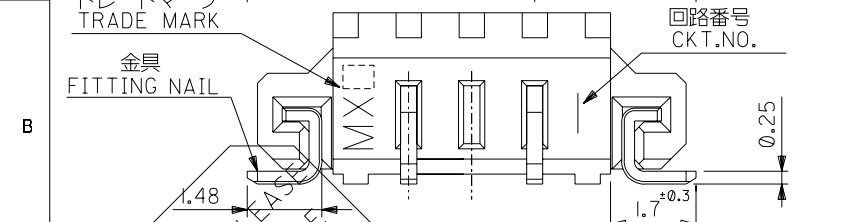
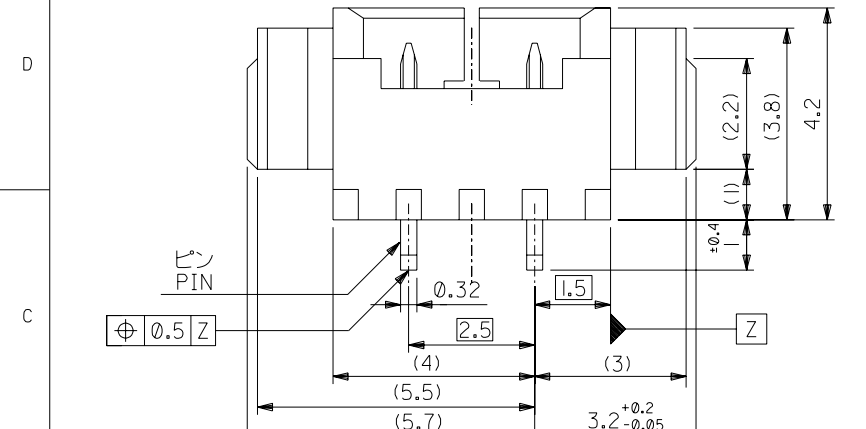
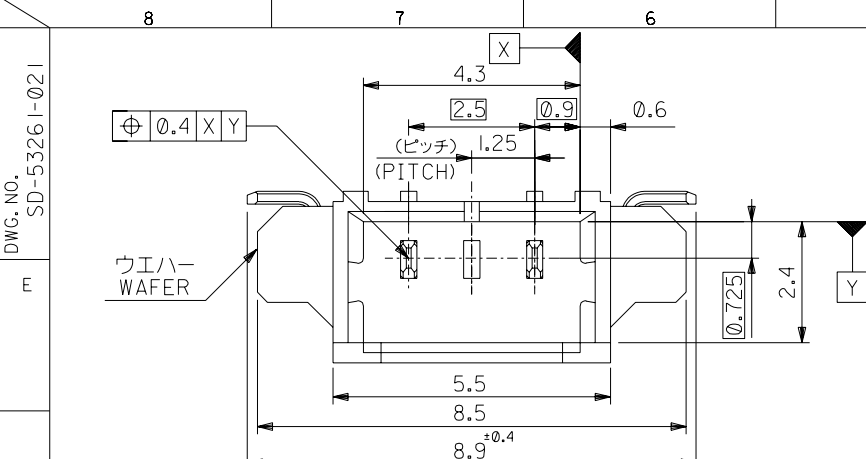
6

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4

3

2



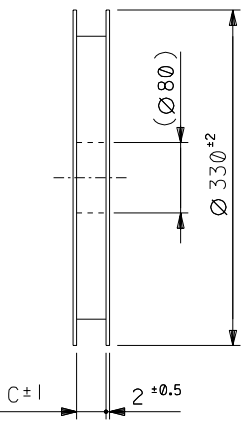
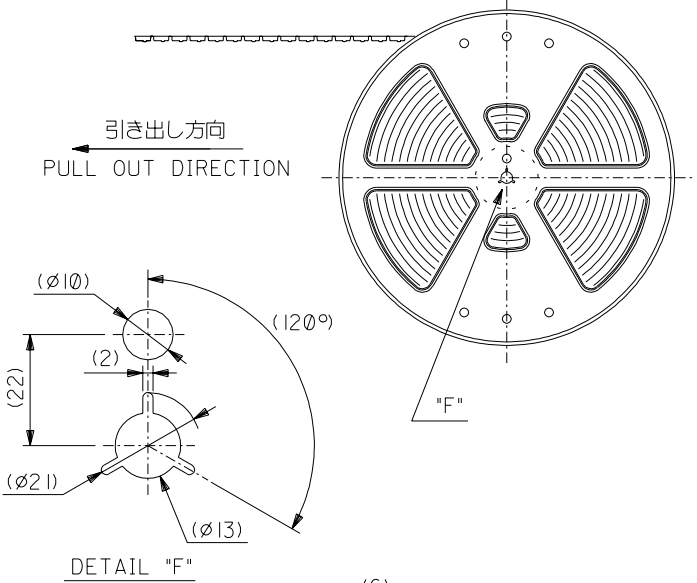
参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)  
(SCALE 5:1)

注記 NOTES

1. 嵌合相手: 51021 シリズ  
MATES WITH: 51021 SERIES
2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
WAFER  
ピン: リン青銅, ニッケル下地, スズメッキ  
PIN: PHOS-BRO., TIN OVER NICKEL PLATING  
金具: リン青銅, ニッケル下地, スズメッキ  
FITTING NAIL: PHOS-BRO.,  
TIN OVER NICKEL PLATING
3. ソルダーテール部のズレ量及び金具(補強板)のズレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。  
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.

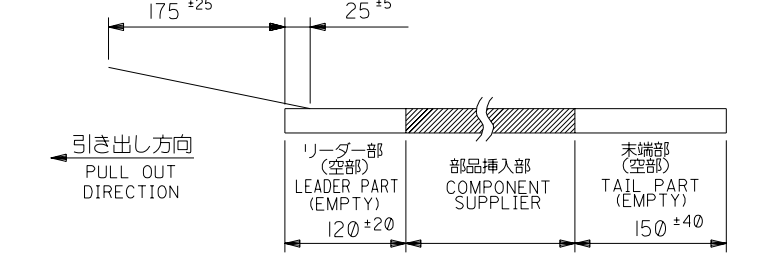
DO NOT SCALE DRAWING

EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		RELEASED ECNO. J2004-2236 DRWN: A.IDA 04/02/03 CH'K: H.TAKASE APPR: J.MIYAZAWA		MATERIAL 材料 注記参照 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE 10-1 DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH		DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY		SHT REV REVISE ON CAD ONLY					
WIRE RANGE 適用層被覆範囲 #		FINISH 仕上げ 注記参照 SEE NOTES		INS. RANGE 被覆外径 #		10 UNDER 未滴 ±0.2 10 OVER 30 UNDER 未滴 ±0.25 30 OVER 以上 ±0.3		DRAWN BY & DATE A. Iida 04/02/03		CHECKED BY & DATE H. Takase 04/02/03		APPROVED BY & DATE J. Miyazawa 04/02/03		TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT RIGHT ANGLE -LEAD FREE-		MOLEX INCORPORATED		CAD FILENAME SD-53261-021.S01		MATERIAL NO. 53261-0329		DRAWING NO. SD-53261-021		SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.														SIZE B											

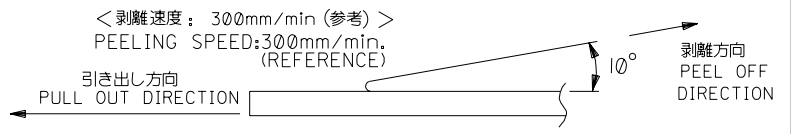


注記  
NOTES

- 53261-022 の詳細寸法については図面 SD-53261-021 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53261-021.
- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダー部 TOP TAPE LEADER PART 175 ±25  
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ±5

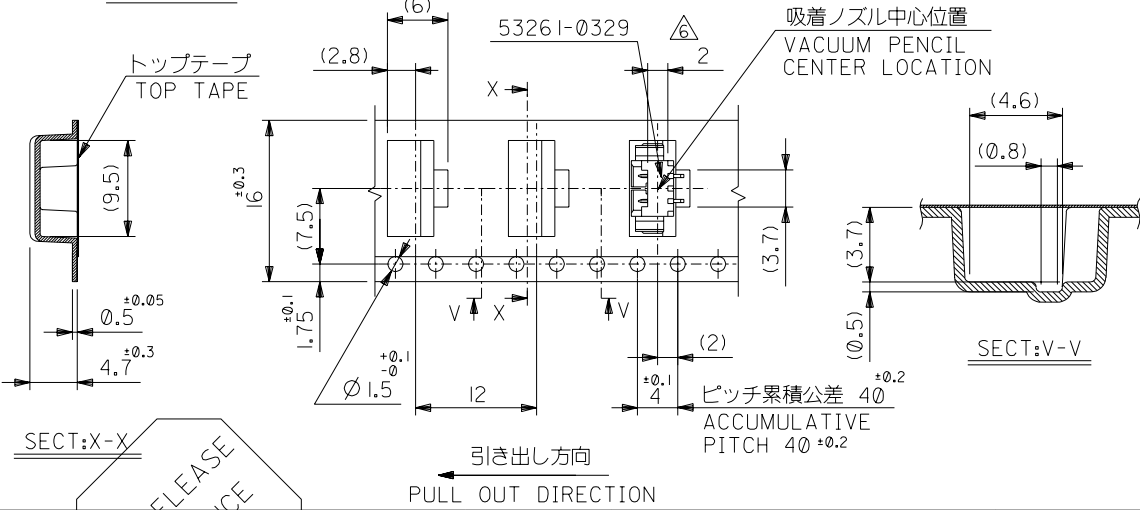


- トップテープの剥離強度: 0.1N~1.3N(10~130gf) (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.1N~1.3N(10~130gf)  
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)



- 材料 (MATERIAL)  
キャリアテープ(CARRIER TAPE): ポリプロピレン(POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA



SECT:X-X  
PRE-RELEASE  
REFERENCE  
USE ONLY

DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASER ECNNO. J2004-2236 DRWN: A.JIDA 04/02/03 CHK: H.TAKASE APPR: J.MIYAZAWA	MATERIAL 材料 注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE #	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
					DESCRIPTION	FINISH 仕上げ 注記参照 SEE NOTES	10 UNDER 未満 ±0.2	DRAWN BY & DATE A. Jida 04/02/03	TITLE: 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR SMT EMBOSSED TAPE PACKAGE -LEAD FREE-			
					WIRE RANGE 適用層被覆範囲		10 OVER 30 UNDER 以上 未満 ±0.25	CHECKED BY & DATE H. Takase 04/02/03	MOLEX INCORPORATED			
					INS. RANGE 被覆外径		30 OVER 以上 ±0.3	APPROVED BY & DATE J. Miyazawa 04/02/03	CAD FILENAME SD-53261-022.S01	MATERIAL NO. 53261-0372	DRAWING NO. SD-53261-022	SHEET NO. 1 OF 1
							ANGLE 角度 ±3°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B